

a surface for supporting the semiconductor wafer, said surface having a concave shape and being configured to cause the semiconductor wafer to contact said surface at the perimeter edge only, said surface having a center portion and an outer portion surrounding said center portion, defining a distance between said center portion and a plane defined by a circle along said outer portion, said circle having a diameter of substantially 300mm and said distance being greater than 500um; and

a heater thermally coupled to said surface for heating said surface.